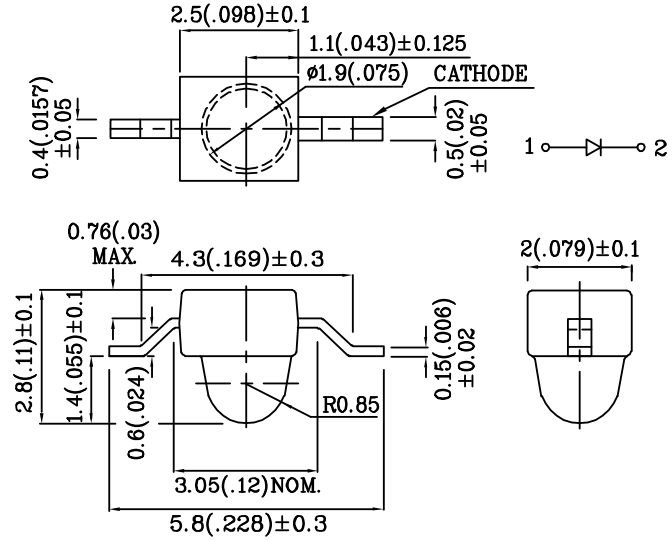


Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.
- RoHS COMPLIANT.



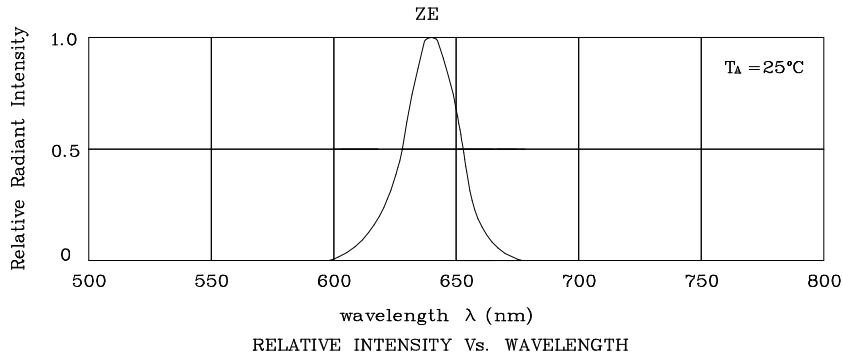
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.

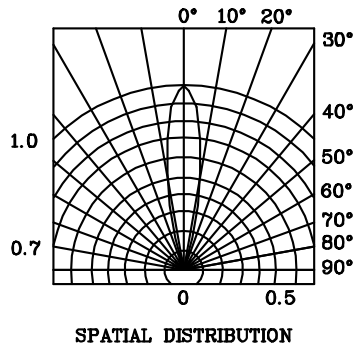
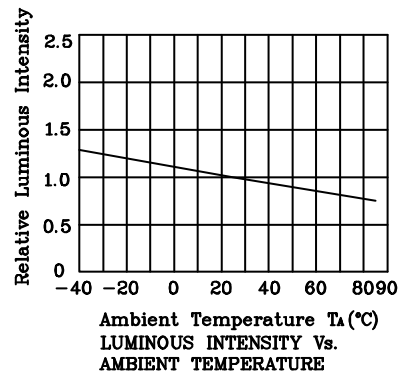
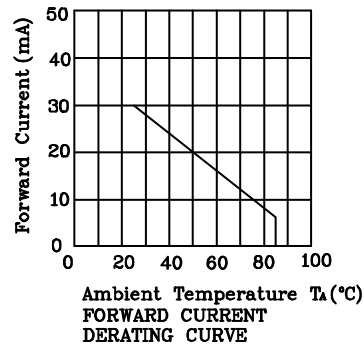
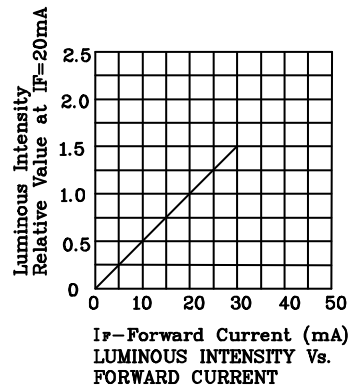
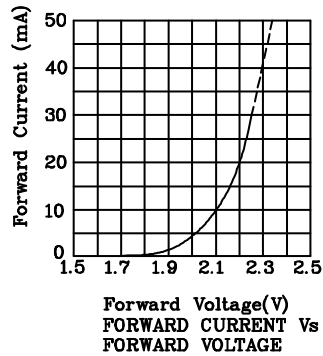
Absolute maximum ratings (TA=25°C)		ZE (InGaAlP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	mA
Power Dissipation	PT	120	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		ZE (InGaAlP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.8	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=20mA)	λ p	640	nm
Wavelength of Dominant Emission (IF=20mA)	λ D	630	nm
Spectral Line Full Width At Half-Maximum (IF=20mA)	Δλ	25	nm
Capacitance (VF=0V, f=1MHz)	C	27	pF

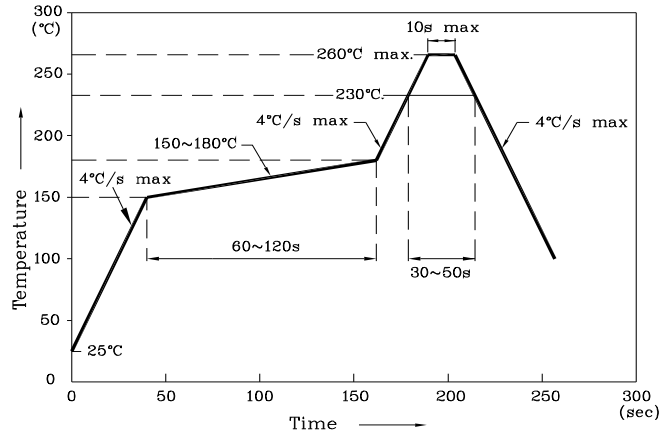
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZZE46W-9	Red	InGaAlP	Water Clear	1500	2490	640	20°



❖ ZE



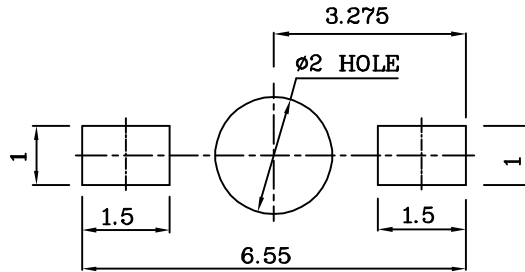
Reflow Soldering Profile For Lead-free SMT Process.



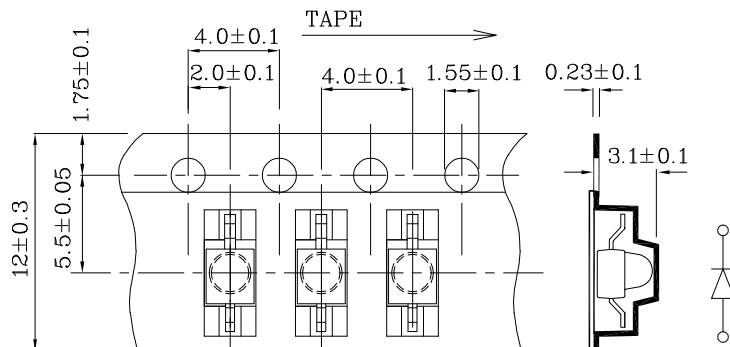
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.1)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.